

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chung-Shi Liu</td> <td>03/28/2007</td> </tr> <tr> <td>Chen-Hua Yu</td> <td>04/12/2007</td> </tr> </tbody> </table>		Name	Execution Date	Chung-Shi Liu	03/28/2007	Chen-Hua Yu	04/12/2007
Name	Execution Date						
Chung-Shi Liu	03/28/2007						
Chen-Hua Yu	04/12/2007						
RECEIVING PARTY DATA							
Name:	Taiwan Semiconductor Manufacturing Co., Ltd.						
Street Address:	No. 8, Li-Hsin Road 6						
Internal Address:	Science-Based Industrial Park						
City:	Hsin-Chu						
State/Country:	TAIWAN						
Postal Code:	300-77						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11733556</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11733556		
Property Type	Number						
Application Number:	11733556						
CORRESPONDENCE DATA							
Fax Number:	(215)979-1020						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
Phone:	(215) 979-1250						
Email:	lambriodes@duanemorris.com						
Correspondent Name:	Steven E. Koffs, Duane Morris LLP						
Address Line 1:	30 South 17th Street						
Address Line 4:	Philadelphia, PENNSYLVANIA 19103-4196						
ATTORNEY DOCKET NUMBER:	N1085-00475						
NAME OF SUBMITTER:	Steven E. Koffs						

Total Attachments: 3
 source=2006-0839-signed assignment-#page1.tif
 source=2006-0839-signed assignment-#page2.tif

CH \$40.00 11733556

Serial No. 11/733,556

Filed: 04/10/2007

2006.0839&840&2007.0057/1085.475

ASSIGNMENT AND AGREEMENT

For value received, we, **Chung-Shi Liu and Chen-Hua Yu**, hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **METHODS FOR FORMING INTERCONNECT STRUCTURES** described in an application for Letters Patent of the United States and all the rights and privileges in said application, and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

2006.0839&840&2007.0057/1085.475

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: 3/28/07

Chung-Shi Liu
Chung-Shi Liu

Residence:

No. 10, Alley 41, Lane 139, Chai-Chiao Road, Shin-Chu, Taiwan, R.O.C.

Inventor No. 2

Dated: _____

Chen-Hua Yu

Residence:

No. 3, 38 Waterfront Road 2, Hsin-Chu, Taiwan, R.O.C.

2006.0839&840&2007.0057/1085.475

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: _____

Chung-Shi Liu

Residence:

No. 10, Alley 41, Lane 139, Chai-Chiao Road, Shin-Chu, Taiwan, R.O.C.

Inventor No. 2

Dated: 4/12/07

Chen-Hua Yu

Residence:

No. 3, 38 Waterfront Road 2, Hsin-Chu, Taiwan, R.O.C.